For immediate release

TAIYO YUDEN Expands Its Product Lineup of Bluetooth® 5 Compatible Wireless Communications Modules
Proposal for increasingly diversifying IoT-related devices such as wearable terminals

TOKYO, October 1, 2019—TAIYO YUDEN CO., LTD. announced today the launch of the new Bluetooth®*1 5 compatible wireless communications module, EYSKJNZWB (5.1×11.3×1.3 mm). This product is most suitable for IoT-related devices that are required to be small and thin, such as wearable terminals, healthcare devices, and physical distribution terminals.

EYSKJNZWB is approximately 75% smaller in volume than our existing product, EYSKBNZWB (15.4×10.0×2.0 mm), which supports the long-range function newly added in Bluetooth® 5.

Mass production of the products will commence in September 2019, with a sample price of 3,000 yen per unit*2.

Technology Background

IoT-related devices are required to operate at extremely low power consumption when used in, for example, sensor networks. Most such devices use Bluetooth® technology as a wireless communications standard with low power consumption. The newest version, Bluetooth® 5, supports new features to meet various needs such as the capability to double communications speed or expand the communications range by up to four times, while retaining the benefit of low power consumption of Bluetooth® V4.2.

EYSKJNZWB is approximately 75% smaller in volume than our existing product, EYSKBNZWB, which supports the long-range function added in Bluetooth® 5. We believe this launch will contribute to the design of smaller, thinner devices.

TAIYO YUDEN will continue to develop more multifunctional and reliable products to expand our product lineup in response to market needs.

*1 The Bluetooth® word mark and logos are owned by Bluetooth SIG, Inc. and the use of such marks by TAIYO YUDEN CO., LTD. is under license.

*2 The sample price mentioned in this release is our direct sales price. When considering purchasing via a sales agency, please contact the agency for the sample price.
## Applications
Wireless communications module for IoT-related devices that are required to be small and thin, such as wearable terminals, healthcare devices, and physical distribution terminals

## Characteristics

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Size (L×W×H)</th>
<th>RAM (kB)</th>
<th>Specification</th>
<th>I/F</th>
<th>Certification</th>
<th>Temperature</th>
</tr>
</thead>
<tbody>
<tr>
<td>EYSKJNZWB</td>
<td>5.1×11.3×1.3 mm</td>
<td>256</td>
<td>V5.0, BLE, Single, 2Mbps, Long Range</td>
<td>UART, SPI, I²C, PDM, I2S, USB</td>
<td>Japan, U.S.A., Canada</td>
<td>-40～+85℃</td>
</tr>
</tbody>
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*3 The ETSI EN 300 328 v2.1.1 test report can be provided.